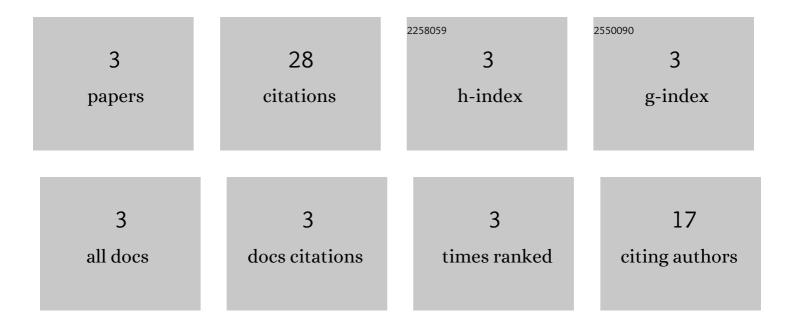
## Xu Fang

## List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/2427717/publications.pdf Version: 2024-02-01



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#	Article	IF	CITATIONS
1	A Post-Bond TSV Test Method Based on RGC Parameters Measurement. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 506-519.	2.7	12
2	TSV Prebond Test Method Based on Switched Capacitors. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2019, 27, 205-218.	3.1	7
3	TSV-Defect Modeling, Detection and Diagnosis Based on 3-D Full Wave Simulation and Parametric Measurement. IEEE Access, 2018, 6, 72415-72426.	4.2	9